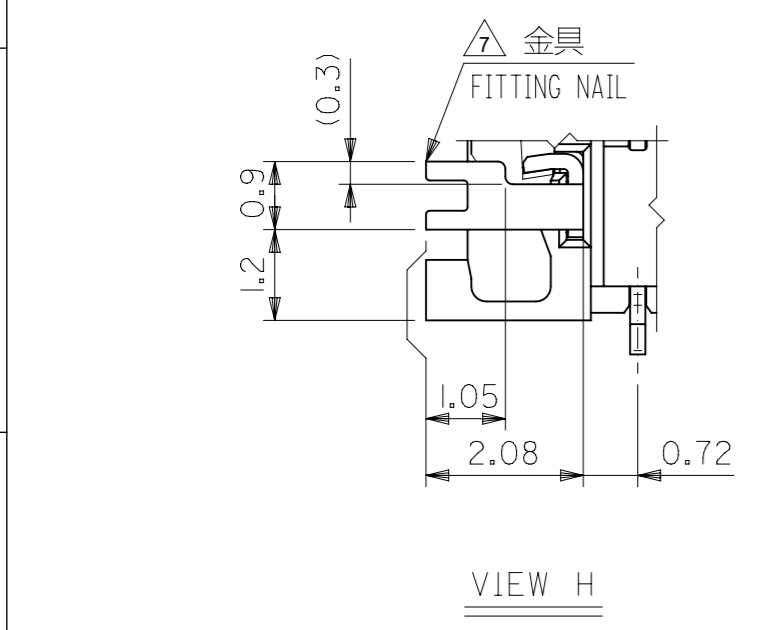


0.3 ± 0.03	10.65	14	9.5	15.2	54548-2033	54548-2022	20
	7.65	11	6.5	12.2	54548-1433	54548-1422	14
	7.15	10.5	6	11.7	54548-1333	54548-1322	13
	6.65	10	5.5	11.2	54548-1233	54548-1222	12
	5.65	9	4.5	10.2	54548-1033	54548-1022	10
	4.65	8	3.5	9.2	54548-0833	54548-0822	8
	4.15	7.5	3	8.7	54548-0733	54548-0722	7
	3.65	7	2.5	8.2	54548-0633	54548-0622	6
	3.15	6.5	2	7.7	54548-0533	54548-0522	5
2.65	6.0	1.5	7.2	54548-0433	54548-0422	4	
THICKNESS OF FPC	D	C	B	A	EMBOSSSED TAPE ORDER No. オーダー番号	製品番号 MATERIAL No.	極数 CIRCUIT



GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 ^{UNDER}	±0.2
10 ^{OVER} 30 ^{UNDER}	±0.25
30 ^{OVER}	±0.3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SCALE: 10:1

GENERAL TOLERANCES (UNLESS SPECIFIED)

DIMENSION UNITS	SCALE
mm	10:1

EC NO: 636343
DRWN: AKUMAR19 2020/04/14
CHK'D: GGA 2020/07/10
APPR: GGA 2020/07/10

INITIAL REVISION:
DRWN: JASANUMA 2013/12/04
APPR: YNOGAWA 2014/01/10

THIRD ANGLE PROJECTION

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

54548-**22 MODEL NO.

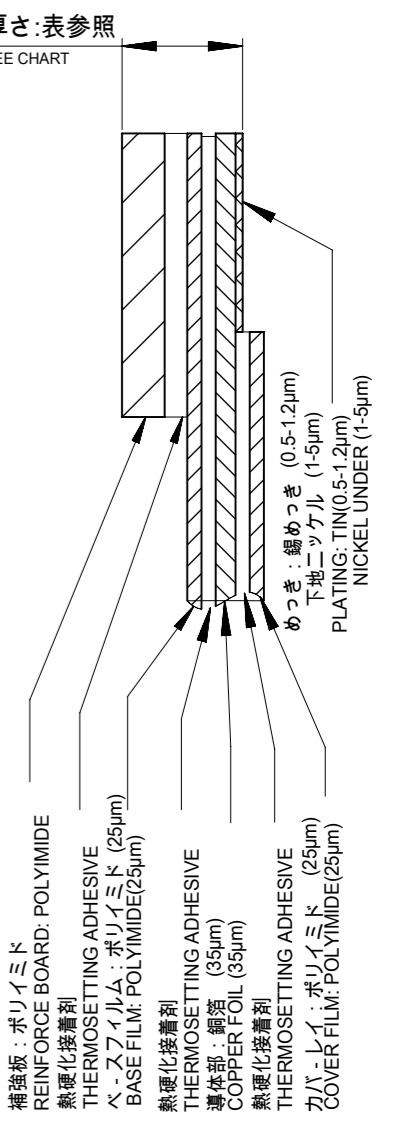
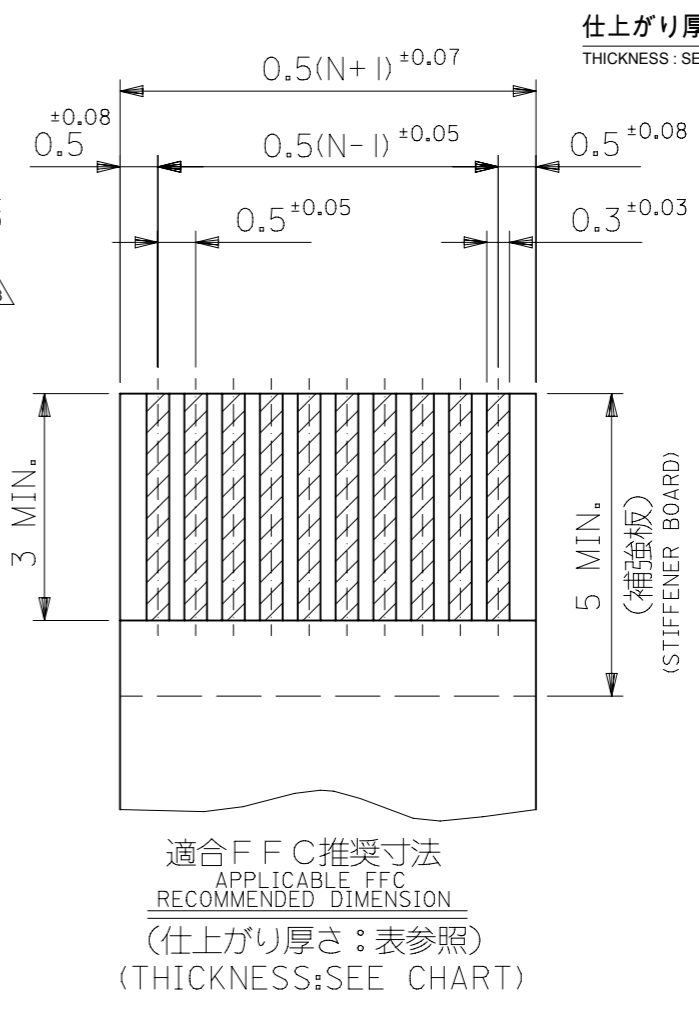
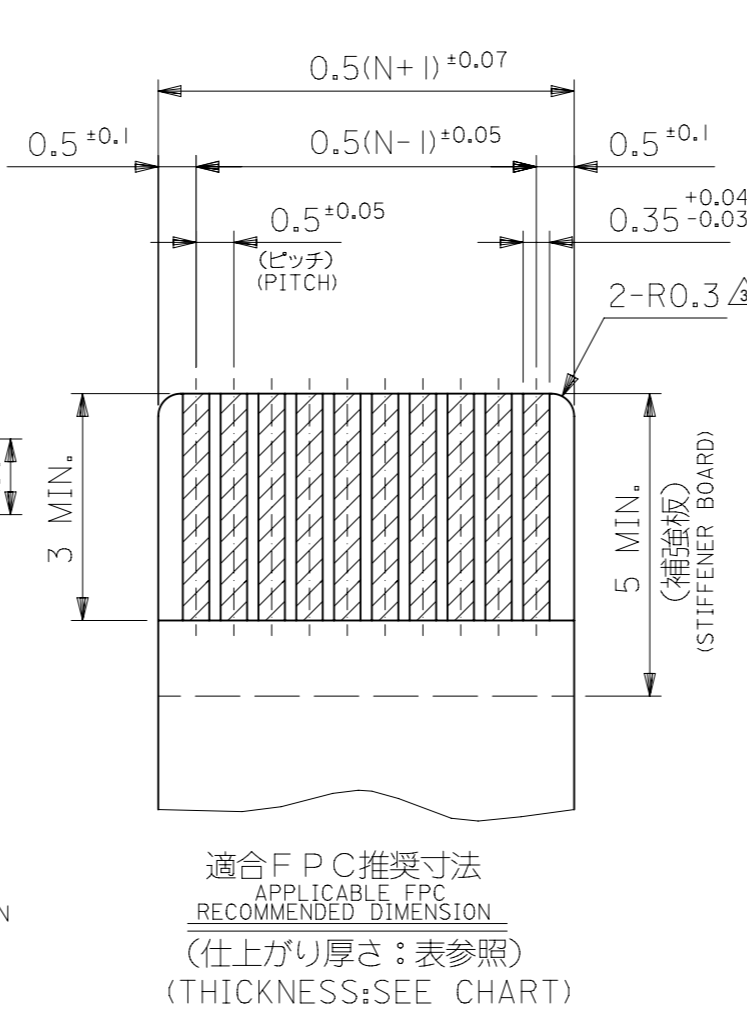
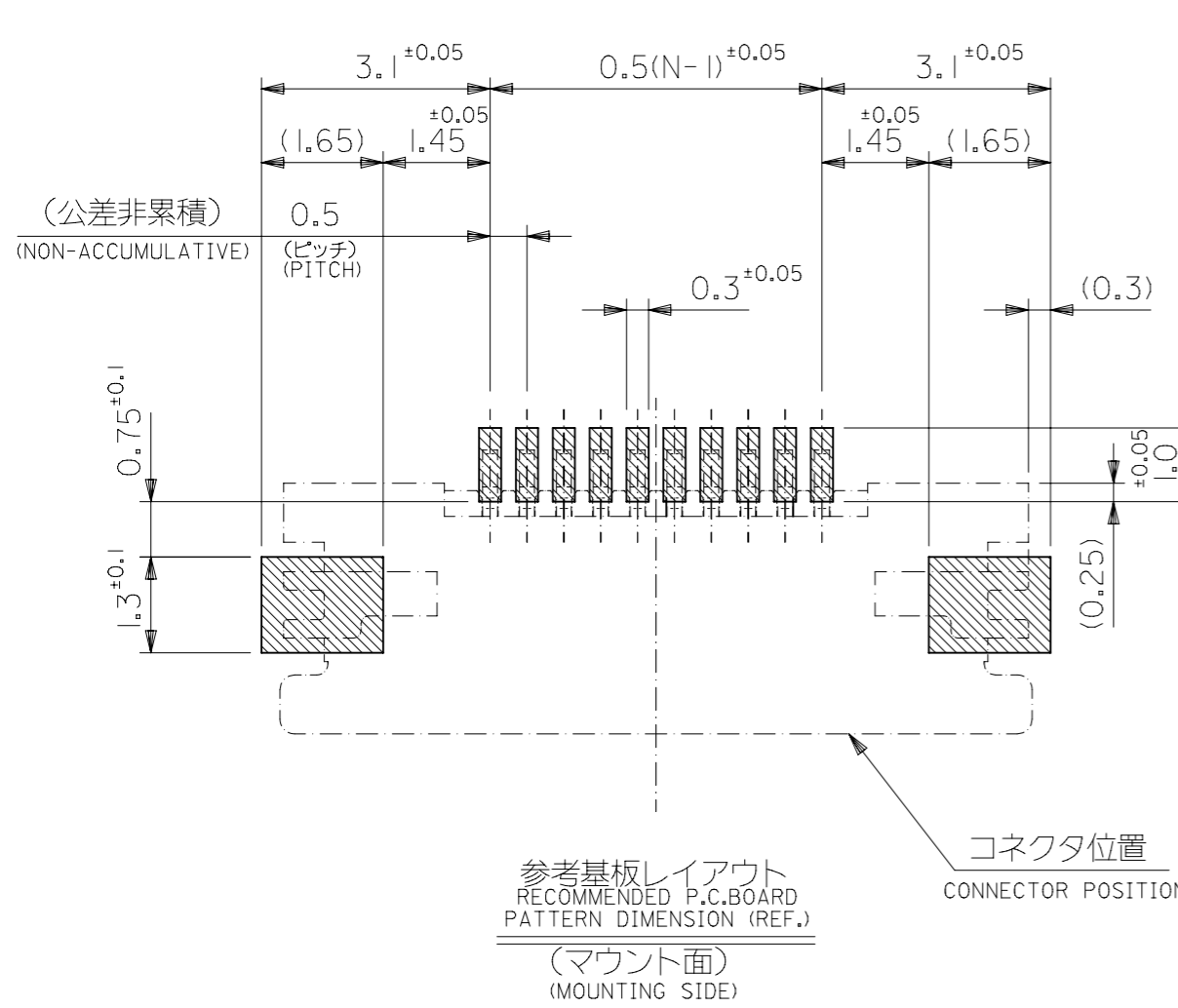
molex

0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER: SD-54548-043
DOC TYPE: PSD
DOC PART: 001
REVISION: A

MATERIAL NUMBER: SEE TABLE
CUSTOMER: GENERAL MARKET
SHEET NUMBER: 1 OF 2



注記 NOTES

1. 使用材料 MATERIAL
- ハウジング : 液晶ポリマー (LCP)、ナチュラル(白色)、ガラス充填、UL94V-0
 HOUSING LIQUID CRYSTAL POLYMER, NATURAL(WHITE), GLASS FILLED, UL-94V0
- アクチュエータ : ポリフェニレンサルファイド(PPS)、黒色ガラス充填、UL94V-0
 ACTUATOR POLYPHENYLENE SULFIDE, BLACK, GLASS FILLED, UL-94V0
- ターミナル : リン青銅 (t=0.2)
 TERMINAL PHOSPHOR BRONZE (t=0.2)
- 金具 : リン青銅 (t=0.2)、
 FITTING NAIL PHOSPHOR BRONZE (t=0.2)
2. めっき仕様 PLATING
- ターミナル TERMINAL
 錫銀ビスマスマッキ(1.0µm以上)
 下地: ニッケルメッキ(1.0µm以上)
 TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATE : NICKEL PLATING (1.0 MICROMETER MINIMUM)
- 金具 FITTING NAIL
 錫メッキ(1.0µm以上)
 下地: ニッケルメッキ(1.0µm以上)
 TIN PLATING
 TIN PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATE : NICKEL PLATING (1.0 MICROMETER MINIMUM)
- △ R0.3はFPCの導体部にかからないこと
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
4. エンボステープ梱包時は、アクチュエータがロックした状態とする。
 IN THE PACKAGE, ACTUATOR OF PART NO.54548-**22 SHOULD BE LOCKED.

- △ ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 0MAX.、下方向 0.15MAX.とし、相互のパラッキ量は0.1MAX.とする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX. OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.
- △ 偶数極に適用。
 APPLY FOR EVEN CIRCUIT.
- △ パターンはくり止め用金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
8. ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT

FPC/FFCについて ABOUT FPC/FFC

打ち抜き方向は導体側から補強板側を推奨します。
 導体部については軟箔銅35µmまたは50µmを推奨します。
 RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
 RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER

FPCについて ABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25µmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 ^{UNDER}	±0.2
10 ^{OVER} 30 ^{UNDER}	±0.25
30 ^{OVER}	±0.3

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54548-**22 MODEL No.

SCALE 1:1

GENERAL TOLERANCES (UNLESS SPECIFIED)

MM		INCH	
4 PLACES	±		
3 PLACES	±		
2 PLACES	±		
1 PLACE	±		
0 PLACES	±		

ANGULAR TOL ± 3.0°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

THIRD ANGLE PROJECTION

DRAWING A3-SIZE

SERIES 54548

MATERIAL NUMBER SEE TABLE

CUSTOMER GENERAL MARKET

SHEET NUMBER 2 OF 2

EC NO: 636343
 DRWN: AKUMAR19 2020/04/14
 CHK'D: GGA 2020/07/10
 APPR: GGA 2020/07/10

INITIAL REVISION:
 DRWN: JASANUMA 2013/12/04
 APPR: YNOGAWA 2014/01/10

DOCUMENT NUMBER SD-54548-043

DOC TYPE PSD

DOC PART 001

REVISION A